Fully-Integrated 10.5 to 13.5 Gbps Transceiver in 0.13μm CMOS

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Outline

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 - Duo-binary coding and the output buffer
- Receiver
 - Quadrature VCO
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 - High gain input buffer
 - DC offset cancellation circuit
 - Data retiming clock phase tuning
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System Overview



Intended applications:

- SONET OC-192 with 7 25 % FEC overhead
- 10G Ethernet with added FEC function and 64/66 code rate
- SOC integration

Transmitter Block Diagram



- Half-rate architecture
- Multiplexer uses CML logic for speed > 2.5GHz

Tx VCO Circuit



- LC oscillator for superior jitter performance
- VCO runs at half the data rate
- Multiple VCO tuning curves to achieve low K_{VCO} and wide range
- Selectable capacitors for coarse tuning, MOS varactors for fine tuning



• Duo-binary coding:

Pre-coding: $p(k) = p(k-1) \oplus x(k)$, Filtering: y(k) = p(k) + p(k-1)

Implementation:

Pre-coding before the last 4:1 MUX Filtering in the output buffer

Transmitter Output Buffer (I)



Output buffer uses four parallel paths:

For normal NRZ pattern: $b_0 = b_1 = b_2 = b_3 = x(k)$ For NRZ with pre-emphasis: $b_0 = b_1 = b_2 = x(k)$, $b_3 = -x(k-1)$ For output duo-binary coding: $b_0 = b_1 = p(k)$, $b_2 = b_3 = p(k-1)$

Transmitter Output Buffer (II)



- Four matched parallel paths
- Inductive peaking in each pre-buffer to improve output rise/fall times
- 50 Ω on chip termination to reduce reflections

Receiver Block Diagram



• Half rate dual loop architecture

Loop-I for VCO training

Loop-II for data phase locking and retiming

- High gain input buffer with DC offset compensation
- Phase tuning of the data sampling clock (Q)

Rx Quadrature LC Oscillator



- Two cross-coupled LC tanks to generate quadrature phases
- Multiple VCO tuning curves to achieve low K_{VCO} and wide range
- Selectable capacitors for coarse tuning, MOS varactors for fine tuning

Binary Phase/DC Offset Detection



ΑΤΒ	Phase	DC offset
0 0 0	-	Decrement if 512 occurrences
0 0 1	retard	decrement
0 1 0	-	-
0 1 1	advance	increment
100	advance	decrement
101	-	-
1 1 0	retard	increment
1 1 1	-	increment if 512 occurrences

Half-Rate Phase Detector Implementation



- Half-rate Alexander phase detector
- Use both edges of In-phase clock to sample the data transition
- Use both edges of quadrature clock to sample the data center
- Automatic 1-to-2 de-multiplexing
- All in CML logic

Data Sampling Clock Phase Tuning



When Di(p,n) has different rise/fall time
(2) is the optimal data sampling point, away from the data center (1)



- α > 0: extra delay to *Ckqo(p,n)*
- *α* < 0: less delay to *Ckqo(p,n)*
- Digitally controlled α provides +/- 45° tuning range, with 6.4° step size



- Digital accumulator "integrates" the T bit to measure input DC offset
- To save power, the digital accumulator runs at lower frequency
- 6 bit current DAC input is thermo-coded to guarantee output monotonic

High Gain Input Buffer (I)



- *los(p,n)*: offset cancellation current
- Two modes of operation:
 - with all 4 stages => high gain for high sensitivity with 1st and 4th stages => low gain for low power
- Active shunt peaking for bandwidth extension

High Gain Input Buffer (II)



- Input-referred offset canceled with current-mode DAC via *I*_{osp}, *I*_{osn}
- NMOS load with active shunt peaking

DC gain ≈



• Equivalent shunt peaking inductance

$$L \approx \frac{R_g}{\omega_{T1}} = \frac{R_g \times C_{gs1}}{g_{m1}}$$



- 0.13 μ m, 1.2v 8M standard CMOS
- Flip-chip layout, wire-bonding package for test chip
- On chip 1.5mm T-lines for high speed I/Os
- 2.0 x 4.0 mm² macro size
- 118-pin PBGA package

Transmitter Test Results(I)



NRZ output @ 10.68Gbps, 2³¹-1 PRBS pattern



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Duo-binary coding @12.5 Gbps, 2³¹-1 PRBS pattern

 Slow edges caused by the non-ideal on-chip T-lines and the wire-bond package

Transmitter Test Results(II)



NRZ output @ 10.3Gbps, 2⁷-1 PRBS pattern

Duo-binary coding @10.3 Gbps, 2⁷-1 PRBS pattern

 Improved output data eyes, the 10G macro is integrated into a XAUI to 10G transceiver in a 400 pin Flip Chip Plastic BGA (FC-PBGA) package



Transmitter Test Results(III)





Tx half rate clock jitter: 1.2ps rms, 8.4ps p-p jitter @ 5.5GHz Tx clock spectrum Phase noise:-103dBc/Hz @ 1MHz offset

Receiver Test Results(I)





Recovered divide-by-4 clock, input 40mV, 2³¹-1 PRBS pattern, 11.0Gbps, 2.46ps rms, 12ps p-p jitter Recovered divide-by-4 clock Spectrum, phase noise: -122dBc/Hz @ 1MHz offset

Receiver Test Results(II)



Rx jitter tolerance: input 40mV 2³¹-1 PRBS pattern, 11.0Gbps 10⁻¹² error threshold

Rx input sensitivity: with DC offset cancellation, 2³¹-1 PRBS pattern, 11.0Gbps

Summary of Experimental Results

<u>Parameter</u>	Experimental results
Technology	0.13μm standard CMOS
Speed	10.5 ~ 13.5 Gbps
Rx input sensitivity	< 15 mV single-ended
Tx jitter generation (50kHz – 80MHz)	6.7 mUI rms
Rx jitter generation (50kHz – 80MHz)	8.9 mUI rms
Tx output swing	700 mV p-p differential
Macro size	8.0 mm ²
Power supply	1.2V, 1.8V
Power consumption	Tx = 450mW, Rx = 550mW

- A fully integrated 10.5 to 13.5 Gbps transceiver in 0.13 μm standard CMOS has been demonstrated
- Half-rate architecture has been demonstrated for both Tx and Rx
- Tx output duo-binary coding integrated
- A new DC offset cancellation technique is implemented
- Rx achieves < 15mV input sensitivity
- SONET OC-192 compliant performance achieved